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**CHANG et al.**(10) **Pub. No.: US 2022/0361327 A1**(43) **Pub. Date: Nov. 10, 2022**(54) **SENSOR LENS ASSEMBLY HAVING  
NON-REFLOW CONFIGURATION****G02B 7/00** (2006.01)**H05K 1/02** (2006.01)(71) Applicant: **KINGPAK TECHNOLOGY INC.**,  
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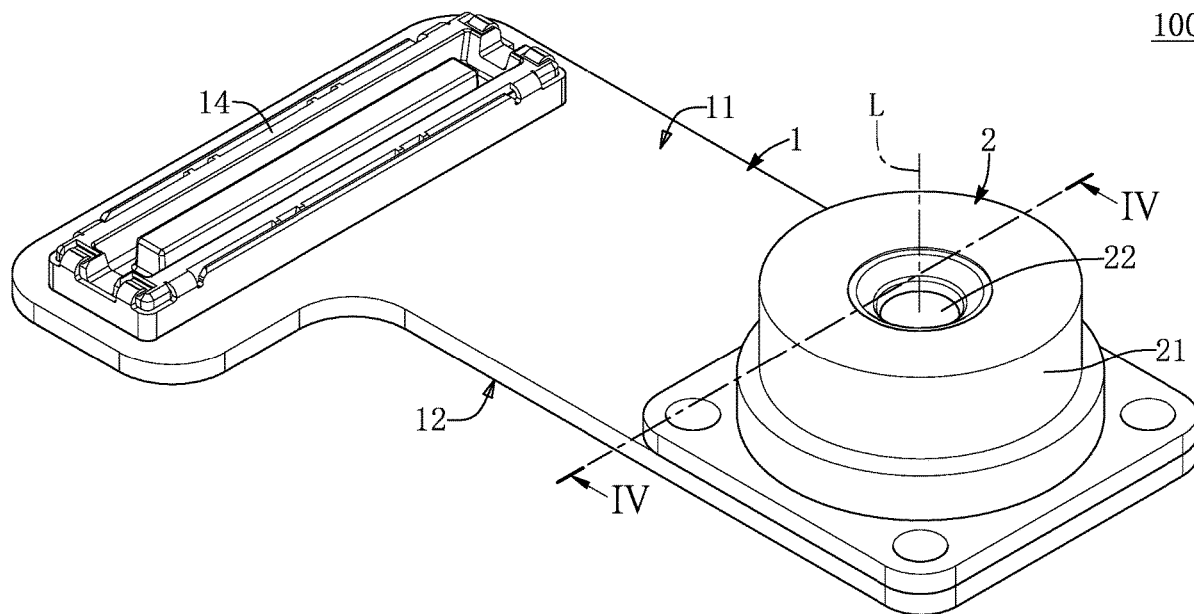
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**ABSTRACT**

A sensor lens assembly having a non-reflow configuration is provided. The sensor lens assembly includes a circuit board, an electronic chip assembled to the circuit board, a sensor chip, a die attach film (DAF) pre-bonded onto the sensor chip, a plurality of wires electrically coupling the electronic chip and the sensor chip to the circuit board, a supporting adhesive layer, a light-permeable sheet, and an optical module that is fixed to the circuit board for surrounding the above components. The sensor chip is adhered to the electronic chip through the DAF such that a sensing region of the sensor chip is perpendicular to a central axis of the optical module. The supporting adhesive layer is in a ringed shape and is disposed on a top surface of the sensor chip. The light-permeable sheet is disposed on the supporting adhesive layer and faces the sensor chip.

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